# MSKSEMI 美森科
## SEMICONDUCTOR
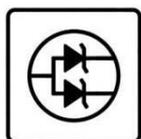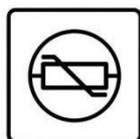
ESD   TVS   TSS   MOV   GDT   PLED

LLDB3/LLDB4

Product specification

These diacs are intended for use in thyristor phase control,circuits for lamp-dimming, universal-motor speed controls, and heat controls.

3.5+/-0.1

Ø1.45+/-0.05

0.3+/-0.1

Cathode Mark
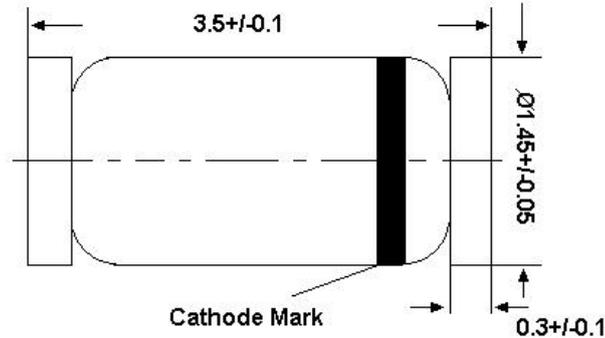
Glass case MiniMELF

Dimensions in mm

LL-34

REEL SPECIFICATION

P/N	PKG	QTY
LLDB3/LLDB4	LL-34	2500

Absolute Maximum Ratings (Ta = 25℃)

Parameter	Symbol	Value	Unit
Power Dissipation (T_a = 65 ^oC)	P_{tot}	150	mW
Repetitive Peak On-state Current (tp = 20 μs, f = 100 Hz)	I_{TRM}	2	A
Operating Junction and Storage Temperature Range	T_j, T_{stg}	- 40 to + 125	^oC

Characteristics at Ta = 25℃)

Parameter		Symbol	Min.	Max.	Unit
Breakover Voltage at C = 22 nF, see diagram 1	LLDB3	V_{BO}	28	36	V
	LLDB4		35	45	
Breakover Voltage Symmetry at C = 22 nF, see diagram 1		$[|+V_{BO}|-|-V_{BO}|]$	-	3	V
Dynamic Breakover Voltage at ΔI = [I_{BO} to I_F = 10 mA]		$|\Delta V \pm|$	5	-	V
Output Voltage See diagram 2		V_O	5	-	V
Breakover Current at C = 22 nF		I_{BO}	-	50	μA
Leakage Current at V_B = 0.5 V_{BO} max		I_B	-	10	μA
Rise Time See diagram 3		t_r	-	2	μs

Diagram 1:   Current-voltage characteristics
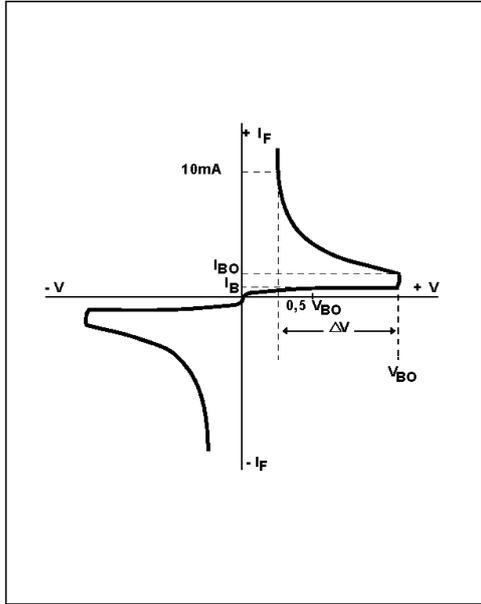

Diagram 2:   Test circuit for output voltage
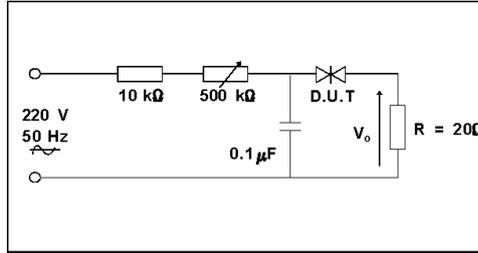
Diagram 3:   Test circuit see diagram 2.
Adjust R for Ip=0.5A
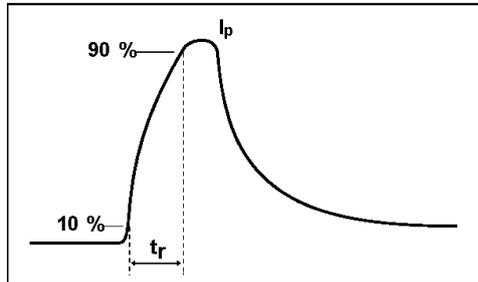
Fig. 1: Power dissipation versus ambient tempera-
ture (maximum values)
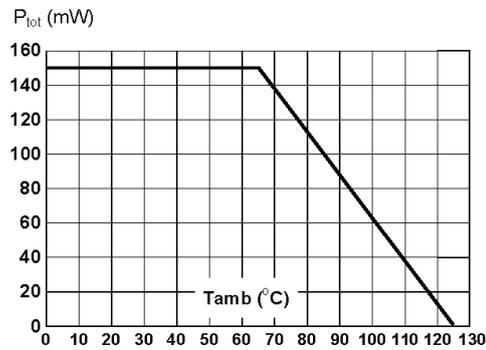
Fig. 2: Relative variation of V_{BO} versus junction
temperature (typical values)
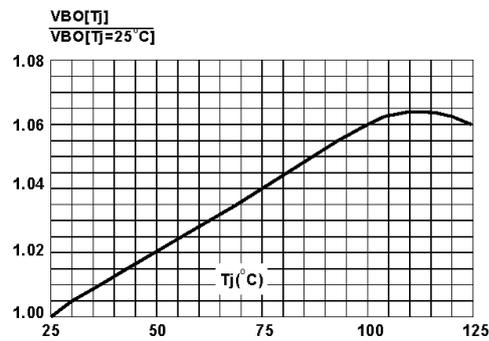
Fig. 3: Peak pulse current versus pulse duration
(maximum values)
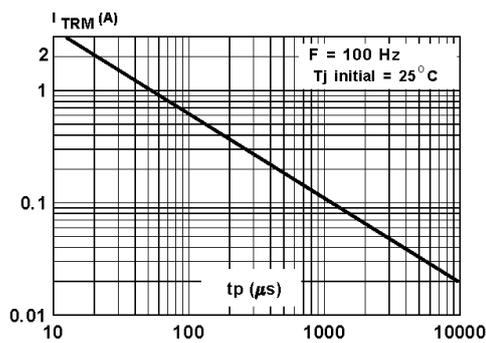
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